**2015 IEEE Compound Semiconductor IC Symposium**

**INTEGRATED CIRCUITS and DEVICES in GaAs, InP, GaN, SiGe, and other compound semiconductor and CMOS technologies**

**October 11–14, 2015**

**Sheraton Hotel, New Orleans, USA**

**Sponsored by the IEEE Electron Devices Society**

**Technically co-sponsored by the Solid State Circuits Society**

**and the Microwave Theory & Techniques Society**

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**BREAKING NEWS - CALL FOR PAPERS**

2015 CSIC Symposium

From its beginning in 1978 as the GaAs IC symposium, the IEEE Compound Semiconductor IC Symposium (CSICS) has evolved to become the preeminent international forum for developments in compound semiconductor integrated circuits and devices, embracing GaAs, InP, GaN, SiGe, and CMOS technology. Coverage includes all aspects of the technology, from materials, device fabrication, IC design, testing, and system applications. CSICS provides the ideal forum to present the latest results in high-speed digital, analog, microwave, millimeter wave, THz, mixed-mode, and opto-electronic integrated circuits. First-time papers addressing the utilization and application of InP, GaAs, GaN, Silicon, Germanium, SiGe, and other compound semiconductors in military and commercial products are invited. Specific technical areas of interest include:

- Innovative device concepts in emerging technologies
  - GaN, InP, III-V on Si, Ge on Si, Graphene
- Analog, RF, mixed-signal, mm-wave, THz circuit blocks and ICs in III-V, CMOS, SiGe BiCMOS
- High-speed digital systems
- Wireless handhelds and base stations
- Vehicular and military RADAR
- Fiber optics and photonics
- Device design and circuit modeling / EM and EDA tools
- Thermal simulation and advanced packaging of high-power devices and ICs
- System applications
- Device and IC manufacturing processes, testing methodologies, & reliability

**Symposium Highlights**

High quality technical papers will be selected from worldwide submissions for oral presentation and publication in the Symposium Digest. Invited papers and panel sessions will complete the program. Extended versions of selected papers from the Symposium will be published in a special issue of the IEEE Journal of Solid State Circuits.

**Primer Course**

On Sunday, Oct. 11th, CSICS will present a primer course, “Introduction to Si RFIC Design,” taught by Dr. W. Khalil (Ohio State). This course is intended for participants of all technical backgrounds who wish to learn or refresh their knowledge in the fundamentals of designing the principal circuit building blocks in radio and radar SOCs. The primer is an excellent way to start the symposium and is guaranteed to enhance attendee appreciation of the technical program.

**Short Courses**

On Sunday, Oct. 11th, 2015 CSICS is proud to present two short courses: “Transmit and Receive IC Design for Fiber Optic Links” and “Microwave Package Design Fundamentals”. Taught by leading experts, they are intended for both technologists and IC designers who seek a comprehensive understanding of the latest trends and techniques in circuit and package design. Organizer: Jim Carroll, AWR-NI Group, Ph: +1-469-248-5462, E-mail: jim.carroll@awrCorp.com.

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**Deadline for Electronic Receipt of Papers is Close of Business, July 10, 2015**

Authors must submit a paper (not more than 4 pages including figures and other supporting material) of results not previously published or not already accepted by another conference. Papers will be selected on the basis of the content and measured results.

**The abstract must concisely and clearly state:**

a) The purpose of the work
b) What specific new results have been obtained
c) How it advances the state-of-the-art or the industry
d) References to prior work
e) Sub-committee preference:
   - Advanced Devices and modeling
   - Analog, RF, and Microwave ICs
   - mm-Wave and THz ICs
   - High-Speed digital, Mixed-Signal & Optoelectronic ICs

The paper must include: the title, name(s) of the authors(s), organization(s) represented, corresponding authors’ postal and electronic addresses, and telephone number. A paper template is available from www.csics.org. Please indicate your preference for subcommittee review. The program committee will honor the authors’ preference where possible, but reserves the right to place the paper in other review categories.

**All company and governmental clearances must be obtained prior to submission of the abstract.**

Authors must submit their camera ready papers in PDF format electronically using the www.csics.org web page. They will be informed regarding the results of their submissions by July 15, 2015. Authors of accepted papers will be required to submit to the IEEE their final camera-ready paper on or before July 17, 2015 for publication in the Symposium Technical Digest. The accepted papers may be used for publicity purposes. Portions of these papers may be quoted in magazine articles publicizing the Symposium. Please note on the paper if this is not acceptable. Further questions on paper submission may be addressed to the Symposium Technical Program Chair:

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Ph: +1-310-317-5784
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All Symposium information, including paper submission instructions and a link to our paper submission address is available on the CSICS website at:

www.csics.org
2015 Compound Semiconductor IC Symposium Exhibition

As in past years, the Symposium will sponsor an exhibition of products from various vendors of materials, IC products, processing equipment, test equipment, CAD tools, and foundry services specifically addressing the Compound Semiconductor industry. Numerous vendors will be on-hand to discuss their products and to answer questions.

Inquiries concerning the exhibits should be addressed to:

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The following members of the Technical Program Committee are available for guidance or for answering questions regarding paper preparation:

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